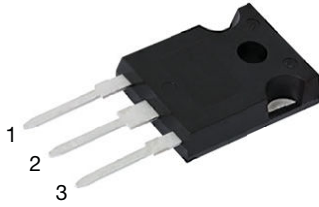
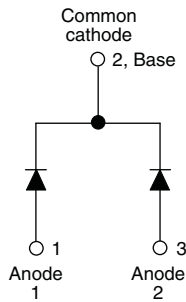


HEXFRED®

Ultrafast Soft Recovery Diode, 2 x 6 A


TO-247AC 3L

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE
BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

VS-HFA12PA120C... is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. The VS-HFA12PA120C... has basic ratings of 1200 V and 6 A per leg continuous current. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA12PA120C... is ideally suited for applications in power supplies and power conversion systems (such as inverters, converters, UPS systems, and power factor correction circuits), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRIMARY CHARACTERISTICS

$I_{F(AV)}$	2 x 6 A
V_R	1200 V
V_F at I_F	2.4 V
t_{rr} typ.	26 ns
T_J max.	150 °C
Package	TO-247AC 3L
Circuit configuration	Common cathode

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		1200	V
Maximum continuous forward current per leg per device	I_F	$T_C = 100\text{ °C}$	6 12	A
Single pulse forward current	I_{FSM}	$t_p = 10\text{ ms}$	80	
Maximum repetitive forward current	I_{FRM}		24	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$ $T_C = 100\text{ °C}$	62.5 25	W
Operating junction and storage temperature range	T_J, T_{Stg}		-55 to +150	°C



ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	$I_R = 100\text{ }\mu\text{A}$	1200	-	-	V
Maximum forward voltage	V_{FM}	$I_F = 6\text{ A}$	-	2.7	3.0	
		$I_F = 12\text{ A}$	-	3.5	3.9	
		$I_F = 6\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	2.4	2.8	
Maximum reverse leakage current	I_{RM}	$V_R = V_R\text{ rated}$	-	0.26	5.0	μA
		$T_J = 125\text{ }^\circ\text{C}, V_R = 0.8 \times V_R\text{ rated}$	-	110	500	
Junction capacitance	C_T	$V_R = 200\text{ V}$	-	9.0	14	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	8.0	-	nH

DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1.0\text{ A}, di_F/dt = 200\text{ A}/\mu\text{s}, V_R = 30\text{ V}$	-	26	-	ns
	t_{rr1}	$T_J = 25\text{ }^\circ\text{C}$	-	53	80	
	t_{rr2}	$T_J = 125\text{ }^\circ\text{C}$	-	87	130	
Peak recovery current	I_{RRM1}	$T_J = 25\text{ }^\circ\text{C}$	-	4.4	8.0	A
	I_{RRM2}	$T_J = 125\text{ }^\circ\text{C}$	-	5.0	9.0	
Reverse recovery charge	Q_{rr1}	$T_J = 25\text{ }^\circ\text{C}$	-	116	320	nC
	Q_{rr2}	$T_J = 125\text{ }^\circ\text{C}$	-	233	585	
Peak rate of fall of recovery current during t_b	$dl_{(rec)M}/dt1$	$T_J = 25\text{ }^\circ\text{C}$	-	180	-	$\text{A}/\mu\text{s}$
	$dl_{(rec)M}/dt2$	$T_J = 125\text{ }^\circ\text{C}$	-	100	-	

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T_{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	$^\circ\text{C}$
Thermal resistance, junction to case	R_{thJC}		-	-	2.0	K/W
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	40	
Thermal resistance, case to heatsink	R_{thCS}	Mounting surface, flat, smooth, and greased	-	0.50	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-247AC 3L	HFA12PA120C			

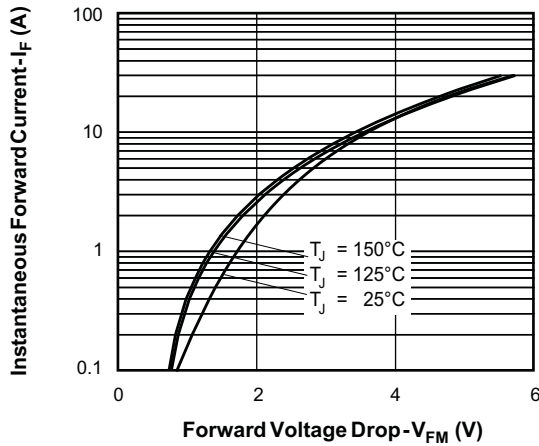


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

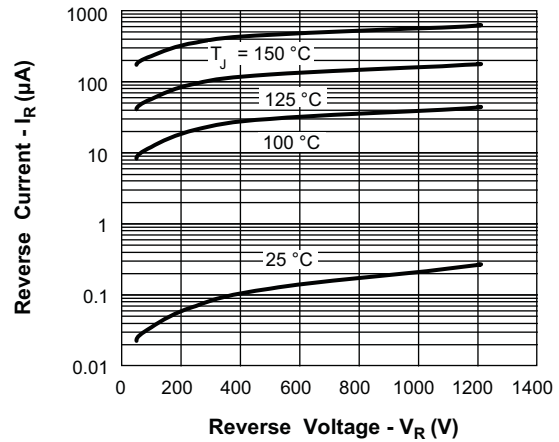


Fig. 2 - Typical Reverse Current vs. Reverse Voltage

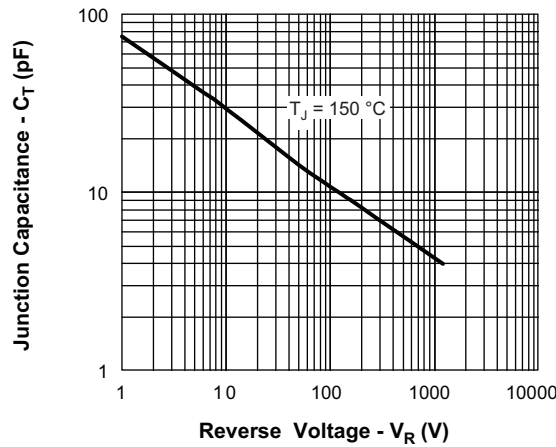


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

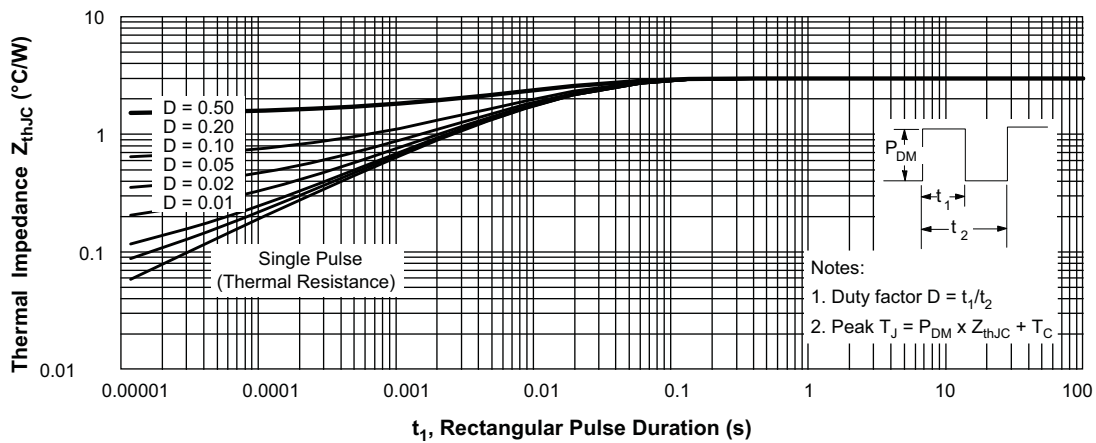


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

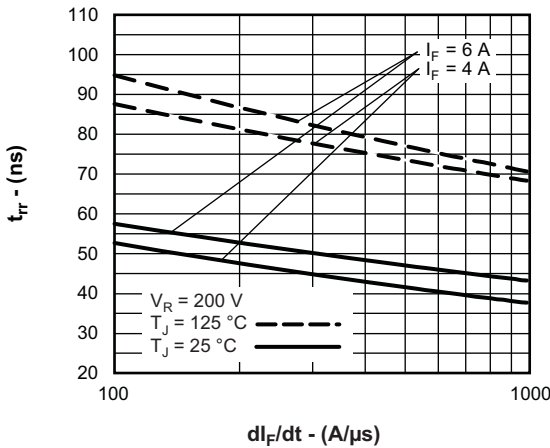


Fig. 5 - Typical Reverse Recovery Time vs. di_F/dt

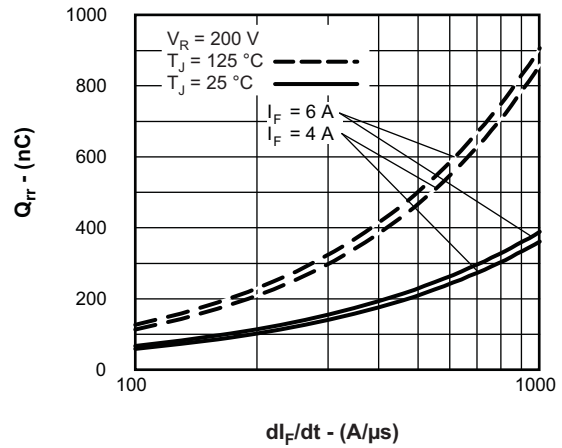


Fig. 7 - Typical Stored Charge vs. di_F/dt

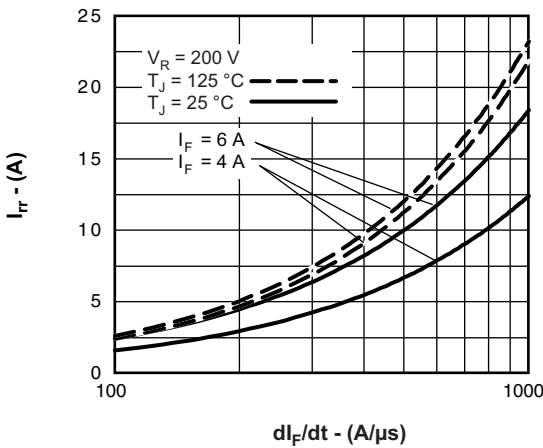


Fig. 6 - Typical Recovery Current vs. di_F/dt

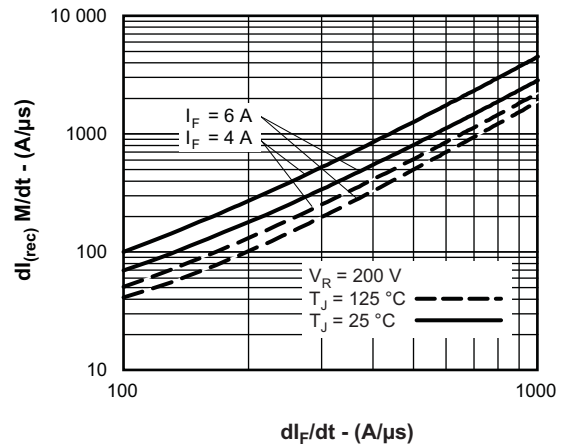
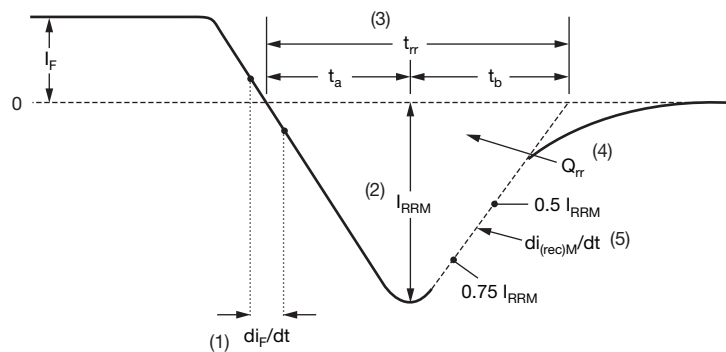


Fig. 8 - Typical $di_{(rec)M}/dt$ vs. di_F/dt



(1) di_F/dt - rate of change of current through zero crossing

(2) I_{RRM} - peak reverse recovery current

(3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.

(4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}

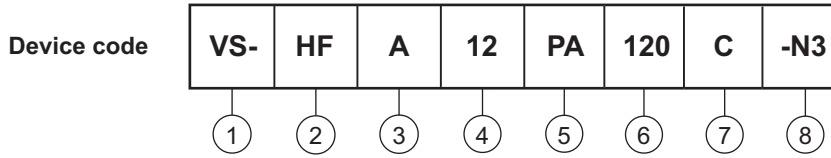
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - HEXFRED® family
- 3** - Electron irradiated
- 4** - Current rating (12 = 12 A)
- 5** - PA = TO-247AC, 3 pins
- 6** - Voltage rating: (120 = 1200 V)
- 7** - Circuit configuration
C = common cathode
- 8** - Environmental digit:
-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-HFA12PA120C-N3	25	500	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96138
Part marking information	www.vishay.com/doc?95007



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